

## APPENDIX

## Changes to Claims:

Claims 30, 36, 40-43 and 45 are canceled.

The following is a marked-up version of the amended claims:

24. (Twice Amended) A semiconductor device, comprising:

a semiconductor chip having a plurality of pads for signal, ~~and~~ a plurality of pads for power source and a plurality of pads for grounding, all of the pads for signal being disposed in areas closer to edges of the semiconductor chip than all of the pads for power source and grounding; and

a flexible substrate having an opening formed therein, the flexible substrate having a power source common lead connected to the pads for power source, the flexible substrate having a grounding common lead connected to the pads for grounding, middle portions of the power source and grounding common leads being continuously positioned inside the opening, and end portions of the power source and grounding common leads being formed on the flexible substrate.

25. (Twice Amended) A semiconductor device, comprising:

a semiconductor chip having a plurality of pads; and

a flexible substrate having an opening formed therein, the flexible substrate having a common lead having an electrical connection branch connected to one of the pads, the common lead having a middle portion, ~~of the common lead~~ the middle portion extending from two edges of the opening and continuously being positioned inside the opening without connection to the pads, and end portions of the common lead being formed on the flexible substrate.

32. (Twice Amended) A semiconductor device, comprising:



a semiconductor chip having a plurality of pads; and

a flexible substrate having an opening formed therein, the flexible substrate having a plurality of leads formed on the flexible substrate and protruding in the opening, the flexible substrate having a common lead, the common lead having a middle portion, of the common lead the middle portion extending from two edges of the opening and being continuously positioned inside the opening, and end portions of the common lead being formed on the flexible substrate,

wherein all of the leads protrude in the opening in a direction different from a direction in which the common lead protrudes in the opening, and

wherein the leads and the common lead are connected to the pads.

34. (Twice Amended) A semiconductor chip, comprising:

a plurality of pads for signal; and

a plurality of pads for power source; and

a plurality of pads for grounding,

wherein all of the pads for signal are disposed in areas closer to edges of the semiconductor chip than all of the pads for power source and grounding.

46. (Twice Amended) A flexible substrate having an opening formed therein, comprising:

a plurality of leads formed on the flexible substrate and protruding in the opening; and

a common lead; having a middle portion, of the common lead the middle portion extending from two edges of the opening and being continuously positioned inside the opening, and end portions of the common lead being formed on the flexible substrate,

wherein all of the leads protrude in the opening in a direction different from a direction in which the common lead protrudes in the opening.